



Telink

Telink Semiconductor (Shanghai) CO., LTD  
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Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		Tongfu Microelectronics Co.,Ltd							
Product Name:		TL8R8258F512ET48							
Weight(Unit):		117.1848	mg					Date:	2023/10/17
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	0.7999	Silicon	7440-21-3	0.7999	100.00%	0.68%	1000000
Die2	GD Die	SMIC BJ	0.2129	Silicon	7440-21-3	0.2129	100.00%	0.18%	1000000
Lead Frame	A194 F.H	Ningbo Kangqiang	59.4167					50.70%	
				Cu	7440-50-8	57.8882	97.43%	49.40%	974275
				Fe	7439-89-6	1.3963	2.35%	1.19%	23500
				Pb	7439-92-1	0.0089	0.02%	0.01%	150
				P	7723-14-0	0.0490	0.08%	0.04%	825
				Zn	7440-66-6	0.0743	0.13%	0.06%	1250
DAF	ATB-120U	Henkel	0.0256					0.02%	
				Epoxy resin A	Trade secret	0.0026	10.0%	0.00%	100000
				Epoxy resin B	Trade secret	0.0036	14.0%	0.00%	140000
				Phenol Resin	Trade secret	0.0036	14.0%	0.00%	140000
				SiO2 Filler	Trade secret	0.0123	48.0%	0.01%	480000
				Acrylic Copolymer	Trade secret	0.0036	14.0%	0.00%	140000
Epoxy	9246LB5	Yihua	0.0962					0.08%	
				Diethylene glycol monoethyl ether acetate	112-15-2	0.0096	10.00%	0.01%	100000
				Silica	15468-32-3	0.0577	60.00%	0.05%	600000
				Acylate resin	Proprietary	0.0144	15.00%	0.01%	150000
				Epoxy resin	Proprietary	0.0135	14.00%	0.01%	140000
				Peroxide	Proprietary	0.0010	1.00%	0.00%	10000
Wire	AGOF	PPM	0.6764					0.58%	
				Ag	7440-22-4	0.6629	98.0000%	0.57%	980000
				others	/	0.0135	2.0000%	0.01%	20000
Mold Compound	EME-G631BQ	Sumitomo	52.7272					45%	
				Epoxy ResinA	Trade secret	1.5818	3.00%	1.35%	30000
				Epoxy ResinB	Trade secret	1.5818	3.00%	1.35%	30000
				Phenol Resin	Trade secret	3.9545	7.50%	3.37%	75000
				Silica(Amorphous) A	60676-86-0	39.7827	75.45%	33.95%	754500
				Silica(Amorphous) B	7631-86-9	3.9545	7.50%	3.37%	75000
				Metal Hydroxide	Trade secret	1.5818	3.00%	1.35%	30000
				Carbon Black	1333-86-4	0.2900	0.55%	0.25%	5500
Plating	TIN	AISEN	3.2299					2.76%	
				Tin	7440-31-5	3.2296	99.99%	2.76%	999900
				Others	Trade Secret	0.0003	0.01%	0.00%	100
Total			117.1848			117.1848	100%	1000000	